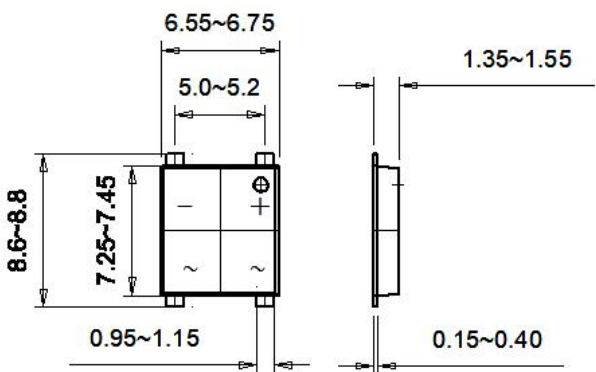




MSB60A thru MSB60M
6A Glass Passivated Single-Phase Bridge Rectifier

特征/Features		外形尺寸/Outline Dimensions	
◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V		Case: MSB Series Dimensions in millimeters  产品尺寸控制范围：±0.2mm 	
机械参数/Machanical Data			
◆ 本体：塑封 Case: plastic package ◆ 标识/极性：本体标记 Marking / Polarity: Marked on Body ◆ 重量：约克 Weight: About 0.24grams			

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25℃ unless otherwise noted									
符号 Symbol	特性 Characteristic	MSB6							单位 Unit
		0A	0B	0D	0G	0J	0K	0M	
VRRM	最大反向重复峰值电压 Maxmum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
IF (AV)	平均整流输出电流 Average Forward Output Rectified Current@Ta =120℃	6							A
VF	正向峰值电压 Forward Voltage Per Leg @IFM =6.0A	1.03							V
IFSM	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	125							A
IR	反向漏电流 Maximum DC reverse current at rated Ta = 25℃ DC blocking voltage per leg Ta = 125℃	5 500							uA
i²t	热容值 Rating for fusing (t<8.3ms)	64.8							A²S
Visol	绝缘耐压 Rms isolation voltage from case to leads	2500							V
CJ	典型结电容 Typical Junction Capacitance	42							pF
RθJC	热阻 Maximum thermal resistance per leg	4.2							℃/W
Tj, TSTG	结温， 存储条件 Operating Junction and storage temperature range	-55～150							℃

Note:

(1) Junction to case with heatsink

(2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .



MSB60A thru MSB60M

6A Glass Passivated Single-Phase Bridge Rectifier

◆ 特性曲线（典型） Characteristics(Typical)

Fig 1-forwardCurrent derating Curve

图1正向电流降额曲线

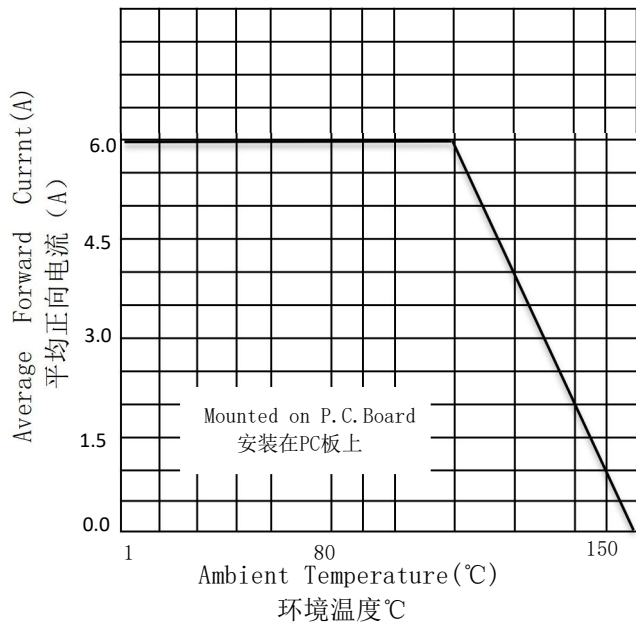


Fig.2-Maximum Non-Repetitive Surge Current

图2 最大不重复正向浪涌曲线

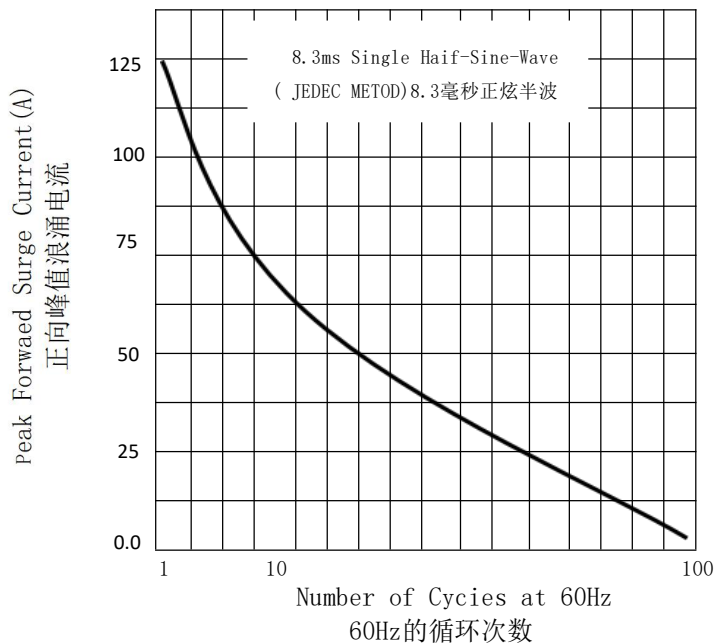


Fig.3-Typical Reverse Characteristics

图3. 典型的反向特性

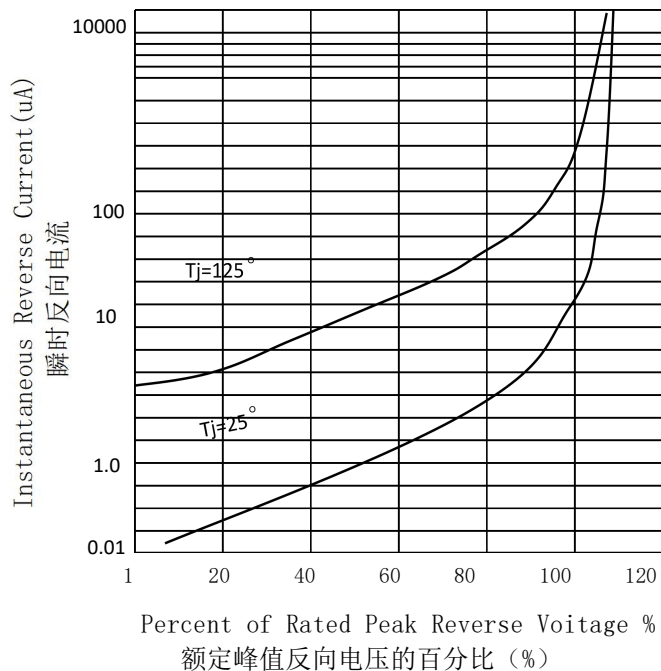
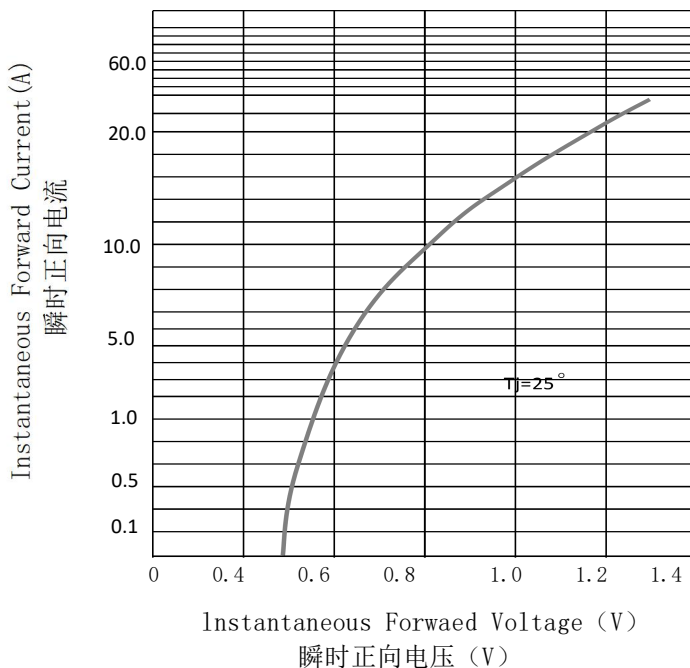


Fig.4-Typical Forward Characteristics

图4. 典型的正向特性

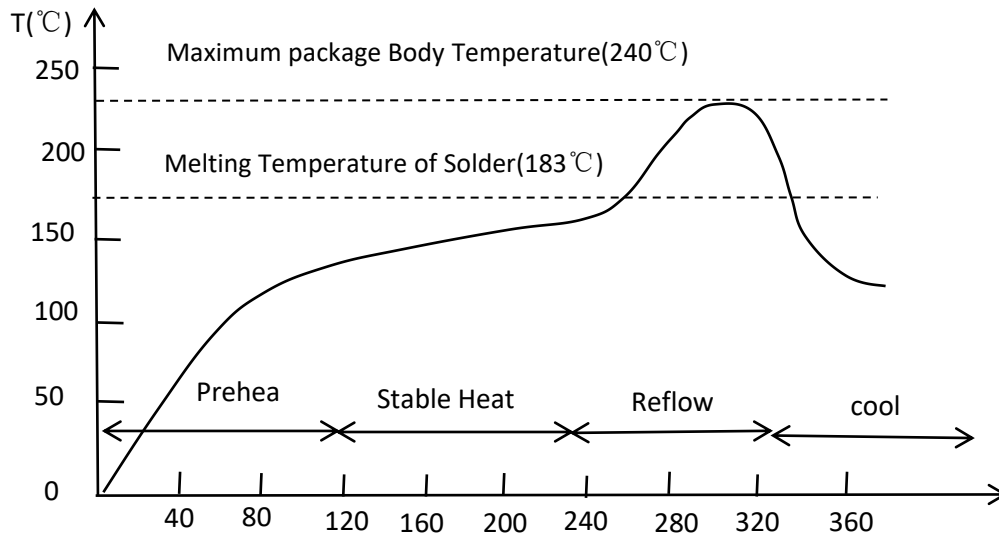




MSB60A thru MSB60M

6A Glass Passivated Single-Phase Bridge Rectifier

◆ 焊接温度 (Suggested Soldering Temperature profile



◆ 回流焊方法: 红外线、气相炉、热风炉、波峰焊

Recommended reflow methods: IR , vapor phase oven , hot air oven , wave solder .

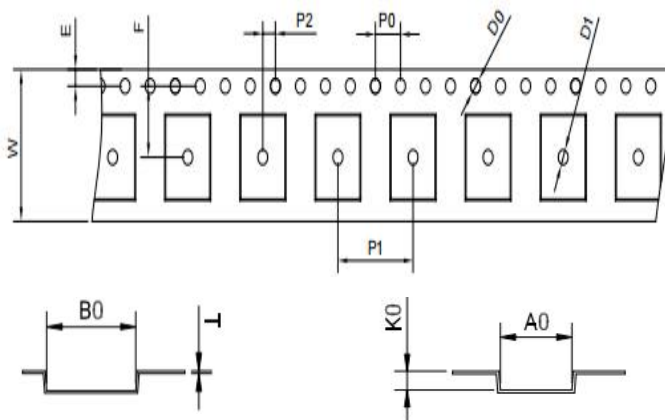
◆ 该装置可在 265° C 的最高温度下暴露 10 秒钟

The device can be exposed to a maximum temperature of 265 ° C for 10 seconds .

◆ 如果回流温度超过建议的温度, 则设备可能不符合性能要求。

If reflow temperatures exceed the recommended profile , devices may not meet the performance requirements .

◆ 载带尺寸 Carrier Dimension(mm)



W	AO	B0	K0	E	F
16	7.05	8.8	1.65	1.75	7.50
D0	D1	P0	P1	P2	T
1.6	1.5	4.0	12.0	2.0	0.25

◆ 包装规格 Package Specifications

Package	Reel Siz	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MSB	13'	330	3	345	6	440*360*360	54